## In the Drawings

Applicant has amended FIG. 5 of the amended drawings previously submitted and entered in order to change an overlapping reference number "43" to --49--.

## In the Specification

Page 7, line 23, replace the paragraph beginning there at with:

The bond pads 16 and layers of busses 24 and 26, routing traces 28, bus 30, and contacts 32 may all be interconnected by vias 38. The busses 24 and 26 may include clearance spaces 42 that electrically isolate the busses 24 and 26 from the vias 38. Additionally, the busses 24 and 26 are also separated by spaces

43.

Page 8, line 1, replace the paragraph beginning there at with:

Figure 4 shows a first conductive strip 44 and a second conductive strip 46 that wrap around an edge of the first bond shelf 18 to connect the bond pads 16 to the power busses 24 and 26. The conductive strips 44 and 46 can be separated by a pair of notches 48 formed in the first bond shelf 18. Some of the bond pads 16 are connected to bus 24 by conductive strip 44 while other bond pads 16 are connected to bus 26 by strip 46. The separate strips allow the bond pads 16 on the first bond shelf 18 to be connected to two different voltage levels. The other bond pads 16 on the first bond shelf 18 may be interconnected to other layers and/or contacts 32 by vias 38.

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